

**500V, N-CHANNEL** 

REF: MIL-PRF-19500/557



# REPETITIVE AVALANCHE AND dv/dt RATED HEXFET® TRANSISTORS THRU-HOLE TO-205AF (TO-39)

**Product Summary** 

Part Number	BVDSS	S RDS(on)	
IRFF430	500V	$1.5\Omega$	2.5A



#### **Description**

The HEXFET® technology is the key to International Rectifier's HiRel advanced line of power MOSFET transistors. The efficient geometry and unique processing of this latest "State of the Art" design achieves: very low on state resistance combined with high trans conductance.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching and temperature stability of the electrical parameters.

They are well suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high energy pulse circuits.

#### **Features**

- Repetitive Avalanche Ratings
- Dynamic dv/dt Rating
- · Hermetically Sealed
- Simple Drive Requirements
- ESD Rating: Class 1C per MIL-STD-750, Method 1020

#### **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
I <sub>D1</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C	Continuous Drain Current	2.5	
I <sub>D2</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C	Continuous Drain Current	1.5	Α
I <sub>DM</sub> @ T <sub>C</sub> = 25°C	Pulsed Drain Current ①	10	
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Maximum Power Dissipation	25	W
	Linear Derating Factor	0.20	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulse Avalanche Energy ②	184	mJ
I <sub>AR</sub>	Avalanche Current ①	2.5	Α
E <sub>AR</sub>	Repetitive Avalanche Energy ①	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.5	V/ns
T <sub>J</sub>	Operating Junction and	-55 to + 150	W/°C V mJ A
T <sub>STG</sub>	Storage Temperature Range	-55 10 + 150	
	Lead Temperature	300 (0.063 in. /1.6 mm from case for 10s)	
	Weight	0.98 (Typical)	g

For Footnotes, refer to the page 2.



### Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	500			V	$V_{GS} = 0V, I_{D} = 1.0 mA$
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.43		V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			1.5	Ω	V <sub>GS</sub> = 10V, I <sub>D2</sub> = 1.5A ④
				1.6		V <sub>GS</sub> = 10V, I <sub>D1</sub> = 2.5A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Gfs	Forward Transconductance	1.5			S	V <sub>DS</sub> = 15V, I <sub>D2</sub> = 1.5A ④
I <sub>DSS</sub>	Zara Cata Valtaria Drain Current			25		$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{V}$
	Zero Gate Voltage Drain Current			250	μA	$V_{DS} = 400V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
$I_{GSS}$	Gate-to-Source Leakage Forward			100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Leakage Reverse			-100	ш	V <sub>GS</sub> = -20V
$Q_G$	Total Gate Charge	19.8		33		I <sub>D1</sub> = 2.5A
$Q_{GS}$	Gate-to-Source Charge	2.2		4.46	nC	V <sub>DS</sub> = 250V
$Q_{GD}$	Gate-to-Drain ('Miller') Charge	5.5		28.11		V <sub>GS</sub> = 10V
t <sub>d(on)</sub>	Turn-On Delay Time			30		V <sub>DD</sub> = 250V
tr	Rise Time			30		$I_{D1} = 2.5A$
t <sub>d(off)</sub>	Turn-Off Delay Time			55	ns	$R_G = 7.5\Omega$
t <sub>f</sub>	Fall Time			30		V <sub>GS</sub> = 10V
Ls +L <sub>D</sub>	Total Inductance		7.0		nH	Measured from Drain lead (6mm / 0.25 in from package) to Source lead (6mm/ 0.25 in from package) with Source wire internally bonded from Source pin to Drain pin
C <sub>iss</sub>	Input Capacitance		610			V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance		135		pF	V <sub>DS</sub> = 25V
$C_{rss}$	Reverse Transfer Capacitance		65			f = 1.0MHz

#### **Source-Drain Diode Ratings and Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Is	Continuous Source Current (Body Diode)			2.5	^	
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①			10	A	
$V_{SD}$	Diode Forward Voltage			1.4	V	$T_J = 25^{\circ}C, I_S = 2.5A, V_{GS} = 0V$
t <sub>rr</sub>	Reverse Recovery Time			900	ns	$T_J = 25^{\circ}C, I_F = 2.5A, V_{DD} \le 50V$
Q <sub>rr</sub>	Reverse Recovery Charge			7.0	μC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrins	ic turn-c	n time i	s negligi	ible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )

#### **Thermal Resistance**

Symbol	Parameter	Min.	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case			5.0	°C/\\/
$R_{\theta JA}$	Junction-to-Ambient (Typical Socket Mount)			175	°C/W

#### Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- $\odot$  V<sub>DD</sub> = 50V, starting T<sub>J</sub> = 25°C, L = 59mH, Peak I<sub>L</sub> = 2.5A, V<sub>GS</sub> = 10V, R<sub>G</sub> = 25  $\Omega$
- $\ \ \, \text{$]$} \quad I_{SD} \leq 2.5 \text{A, di/dt} \leq 75 \text{A/}\mu\text{s, } V_{DD} \leq 500 \text{V, } T_{J} \leq 150 ^{\circ}\text{C, Suggested } R_{G} = 7.5 \; \Omega$
- 4 Pulse width  $\leq 300 \ \mu s$ ; Duty Cycle  $\leq 2\%$

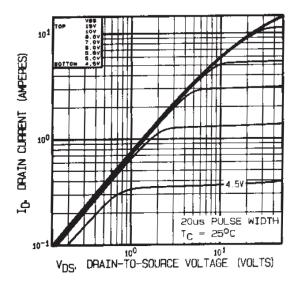


Fig 1. Typical Output Characteristics

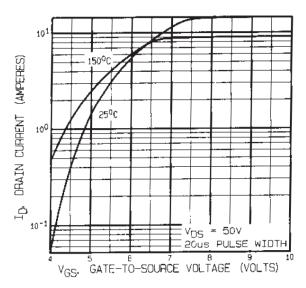
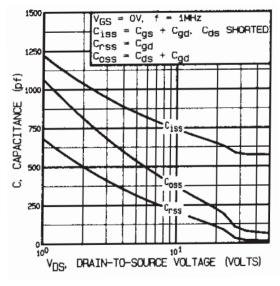


Fig 3. Typical Transfer Characteristics



**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage

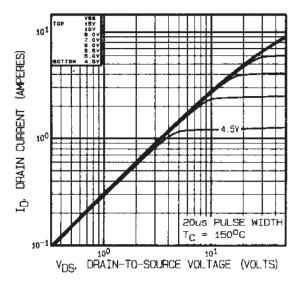


Fig 2. Typical Output Characteristics

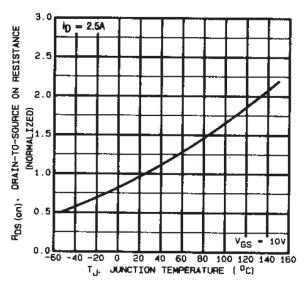
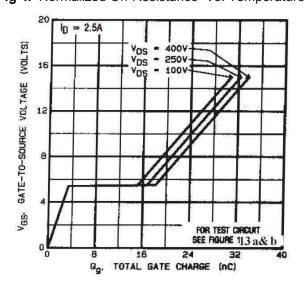
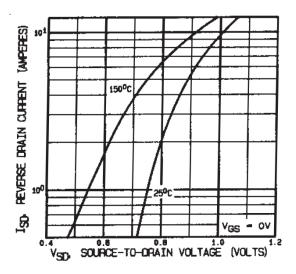


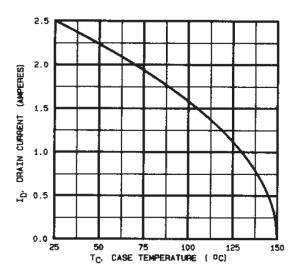
Fig 4. Normalized On-Resistance Vs. Temperature



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 9.** Maximum Drain Current Vs. Case Temperature

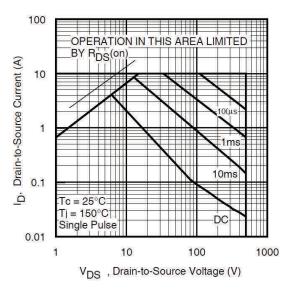


Fig 8. Maximum Safe Operating Area

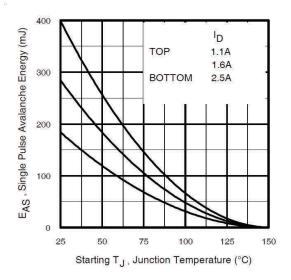


Fig 10. Maximum Avalanche Energy Vs. Drain Current

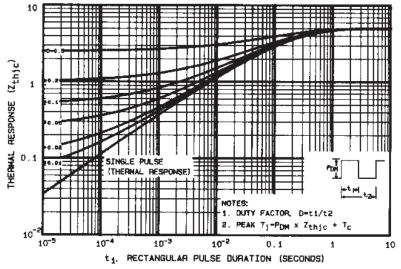


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

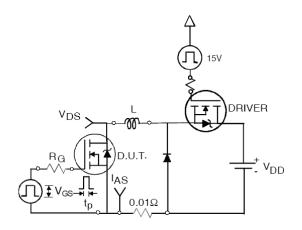


Fig 12a. Unclamped Inductive Test Circuit

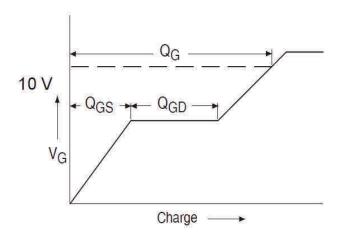


Fig 13a. Gate Charge Waveform

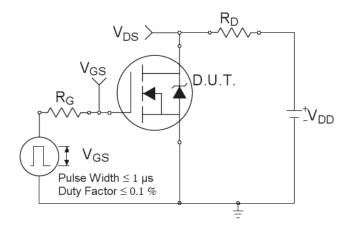


Fig 14a. Switching Time Test Circuit

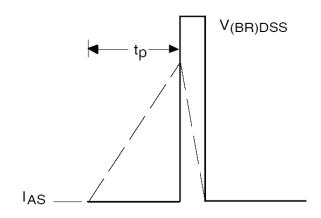


Fig 12b. Unclamped Inductive Waveforms

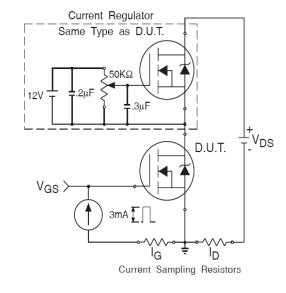


Fig 13b. Gate Charge Test Circuit

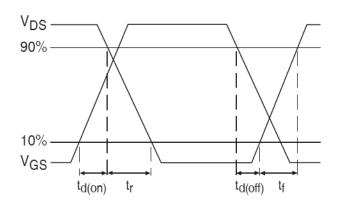
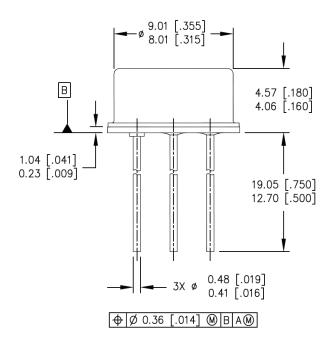


Fig 14b. Switching Time Waveforms



#### Case Outline and Dimensions - TO-205AF (TO-39)

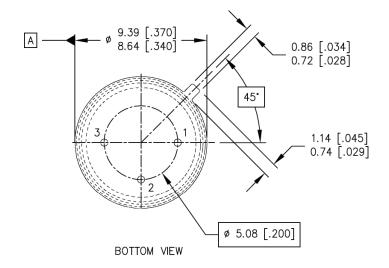


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME 14.5M-1994.

SIDE VIEW

- 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 3. CONTROLLING DIMENSION: INCH.
- 4. CONFORMS TO JEDEC OUTLINE TO-205AF (TO-39).



**LEGEND** 

1- SOURCE

2- GATE

3- DRAIN (CONNECTED TO THE CASE)



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